




SPECIFICATION SHEET

SPECIFICATION SHEET NO.	N0310- SOD323V21WSST3
DATE	Mar. 10, 2021
REVISION	A0
DESCRIPTION	SMD Small Signal Fast Switching diodes, SOD-323 series, 2 pads Reverse Voltage 250V Max. Forward Current 250mA Max. Operating Temp. Range -55°C ~+150°C, Package in Tape/Reel, 3000pcs/Reel RoHS/RoHS III compliant
CUSTOMER	
CUSTOMER PART NUMBER	
CROSS REF. PART NUMBER	
ORIGINAL PART NUMBER	MDD BAV21WS
PART CODE	SOD323V21WSST3

VENDOR APPROVE			
Issued/Checked/Approved			
DATE: March 10, 2021			

CUSTOMER APPROVE	
DATE:	

SMD FAST SWITCHING DIODES SOD323 SERIES



MAIN FEATURE

- Fast switching speed
- Glass Passivated Chip Junction
- Fast reverse recovery time
- High conductance

APPLICATION

- For general purpose switching applications

RFQ

[Request For Quotation](#)

PART CODE GUIDE

SOD323	V21WS	S	T3
1	2	3	4

- 1) **SOD323**: SMD Small Signal Fast Switching diodes, 2 pads, SOD-323 series
- 2) **V21WS**: Type code for original part number BAV21WS
- 3) **S**: Package code, Tape/reel, 3000pcs/reel.
- 4) **T3**: Marking code for “T3” on the case surface, Different Marking for different specification.

MORE ITEMS AVAILABLE

SOD323V21WSST3				

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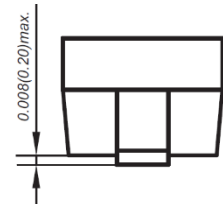
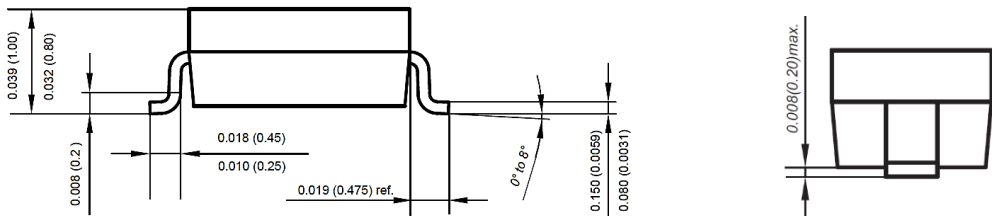
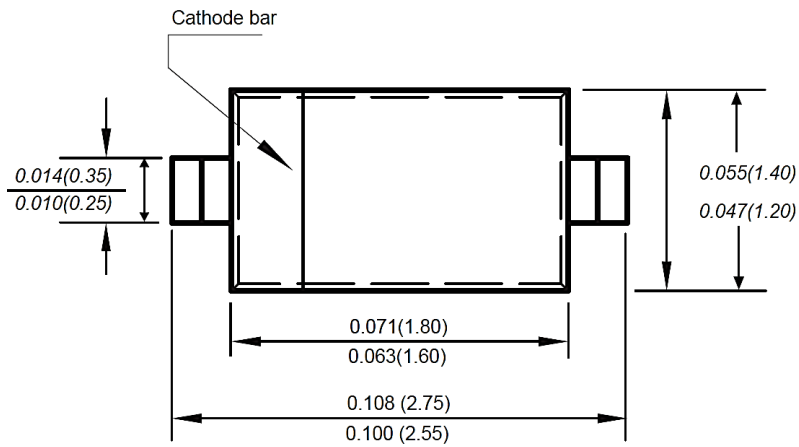
DIMENSION (Unit: Inch/mm)

Image for reference

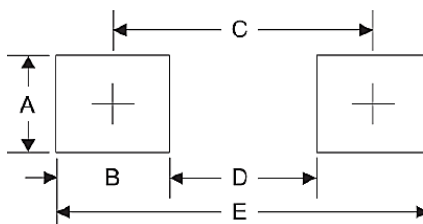


Marking: T3

SOD-323



Recommend Pad Layout



Symbol	Unit (inch)	Unit (mm)
A	0.028	0.70
B	0.028	0.70
C	0.085	2.15
D	0.071	1.80
E	0.112	2.85

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MECHANICAL DATA

Case	Terminals	Polarity	Mounting Position	Weight per piece
JEDEC SOD-323 molded plastic body	Solder plated, Solderable per MIL-STD-750, Method 2026	Polarity symbol marking on case	Any	0.00019 Ounce, 0.00591 grams

ABSOLUTE MAX. RATING AT 25 °C

Parameter	SYMBOLS	VALUE			UNITS
		Min.	Typical	Max.	
Repetitive peak reverse voltage	V _{RRM}			250	Volts
RMS voltage	V _{RMS}			200	Volts
Continuous Forward Current	I _O			250	mA
Repetitive Peak Forward Current	I _{FM}			625	mA
Non-repetitive Peak forward surge current	@ = 1s	I _{FSM}		1	A
	@ = 1 ms			3	
	@ = 1 μs			9	
Total Power Dissipation	P _{tot}			500	mW
Operating Junction temperature range	T _J	-55		+150	°C
Storage temperature range	T _{STG}	-55		+150	°C

Characteristics at Ta= 25 °C

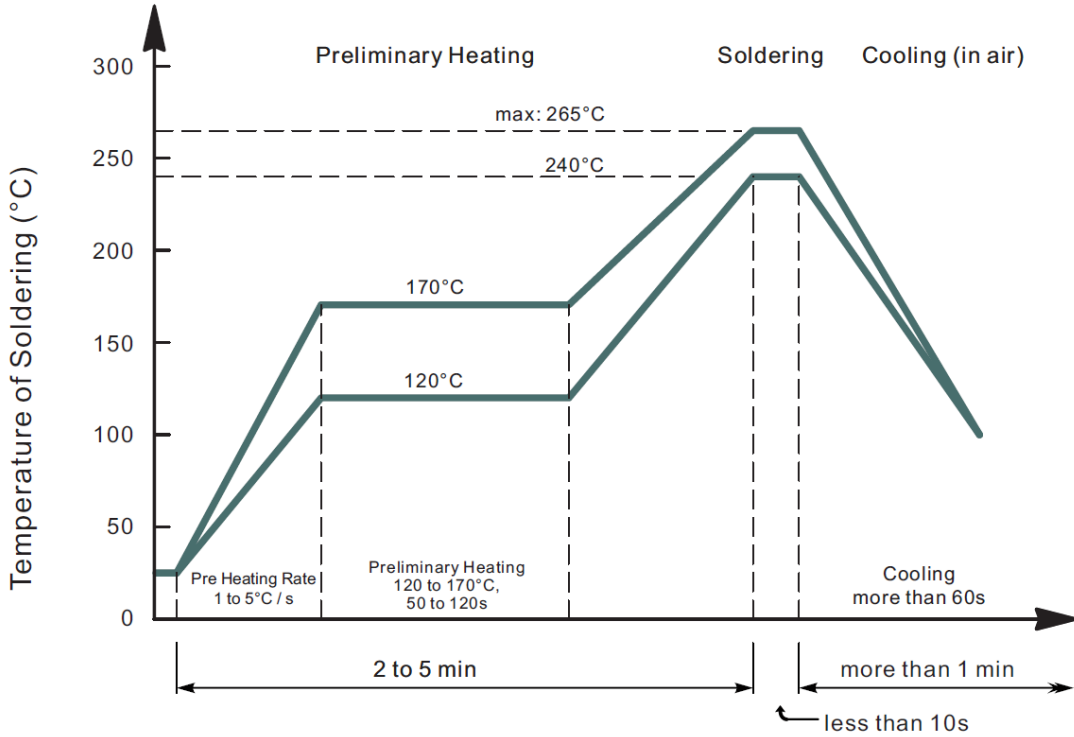
Parameter	SYMBOLS	VALUE			UNIT	Condition
		Min.	Typ.	Max.		
Reverse Current	I _R			0.1	μA	at V _R = 250 V, T _a = 25°C
				100		at V _R = 250 V, T _a = 150°C
Forward Voltage	V _F			1	V	I _F = 100 mA
				1.25		I = 200 mA
Capacitance between terminals	C _{tot}			5	pF	V _R =0V, f=1.0MHz
Reverse recovery time	t _{rr}			50	ns	I _F =0.5 A, I _R =1A I _{rr} =0.25A, R _L =100Ω

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RELIABILITY

Number	Experiment Items	Experiment Method And Conditions	Reference Documents
1	Solder Resistance Test	Test 260°C± 5°C for 10 ± 2 sec. Immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031.2
2	Solderability Test	230°C ±5°C for 5 sec.	MIL-STD-750D METHOD-2026.1 0
3	Pull Test	1 kg in axial lead direction for 10 sec.	MIL-STD-750D METHOD-2036.4
4	Bend Test	0.5Kg Weight Applied To Each Lead, Bending Arcs 90 °C ± 5 °C For 3 Times	MIL-STD-750D METHOD-2036.4
5	High Temperature Reverse Bias Test	TA=100°C for 1000 Hours at VR=80% Rated VR	MIL-STD-750D METHOD-1038.4
6	Forward Operation Life Test	TA=25°C Rated Average Rectified Current	MIL-STD-750D METHOD-1027.3
7	Intermittent Operation Life Test	On state: 5 min with rated IRMS Power Off state: 5 min with Cool Forced Air. On and off for 1000 cycles.	MIL-STD-750D METHOD-1036.3
8	Pressure Cooker Test	15 PSIG, TA=121°C, 4 hours	MIL-S-19500 APPENOIXC
9	Temperature Cycling Test	-55°C~+125°C; 30 Minutes For Dwelled Time 5 minutes for transferred time. Total: 10 cycles.	MIL-STD-750D METHOD-1051.7
10	Thermal Shock Test	0°C for 5 minutes., 100°C for 5minutes, Total: 10 cycles	MIL-STD-750D METHOD-1056.7
11	Forward Surge Test	8.3ms Single Sale Sine-wave One Surge.	MIL-STD-750D METHOD-4066.4
12	Humidity Test	TA=65°C, RH=98% for 1000 hours.	MIL-STD-750D METHOD-1021.3
13	High Temperature Storage life Test	150°C for 1000 Hours	MIL-STD-750D METHOD-1031.5

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SUGGESTED REFLOW PROFILE (For Reference Only)



- Recommended peak temperature is over 245°C, If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)
- Welding shall not exceed 2 times
- Remark: lead free solder paste (96.5 sn/3.0 Ag/0.5Cu)

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RATINGS AND CHARACTERISTIC CURVES (For Reference Only)

Fig.1 Power Derating Curve

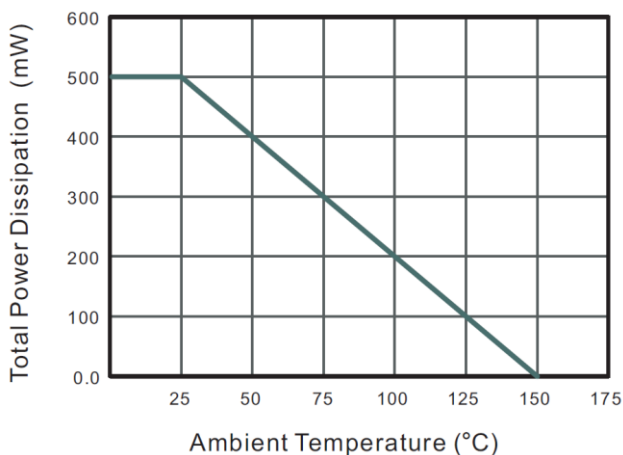


Fig.2 Typical Reverse Characteristics

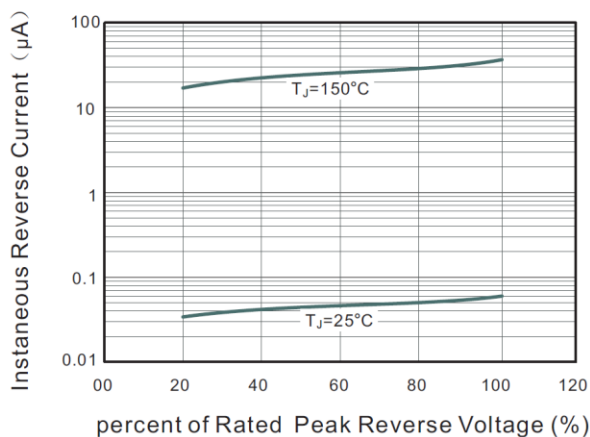


Fig.3 Typical Instantaneous Forward Characteristics

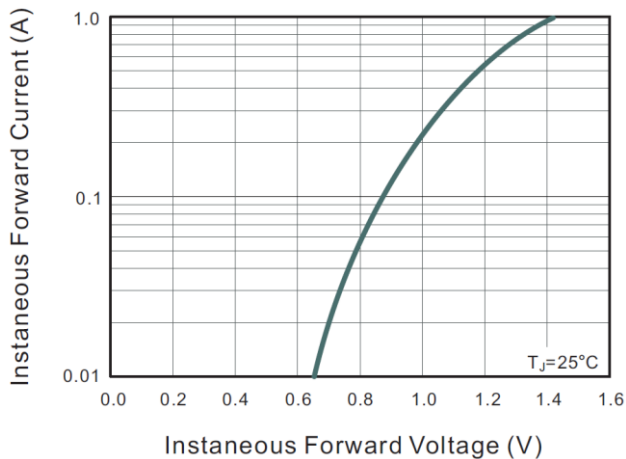
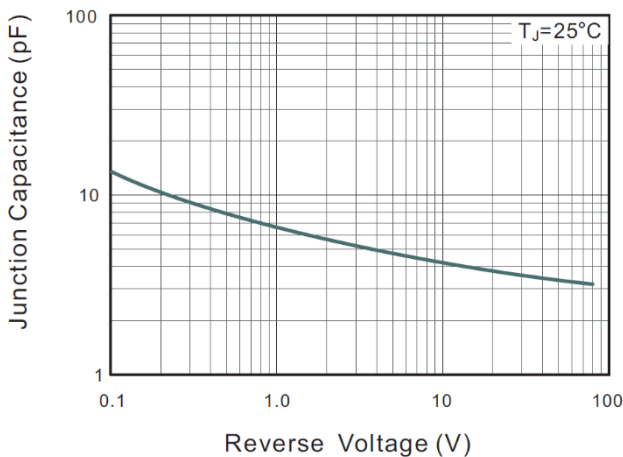


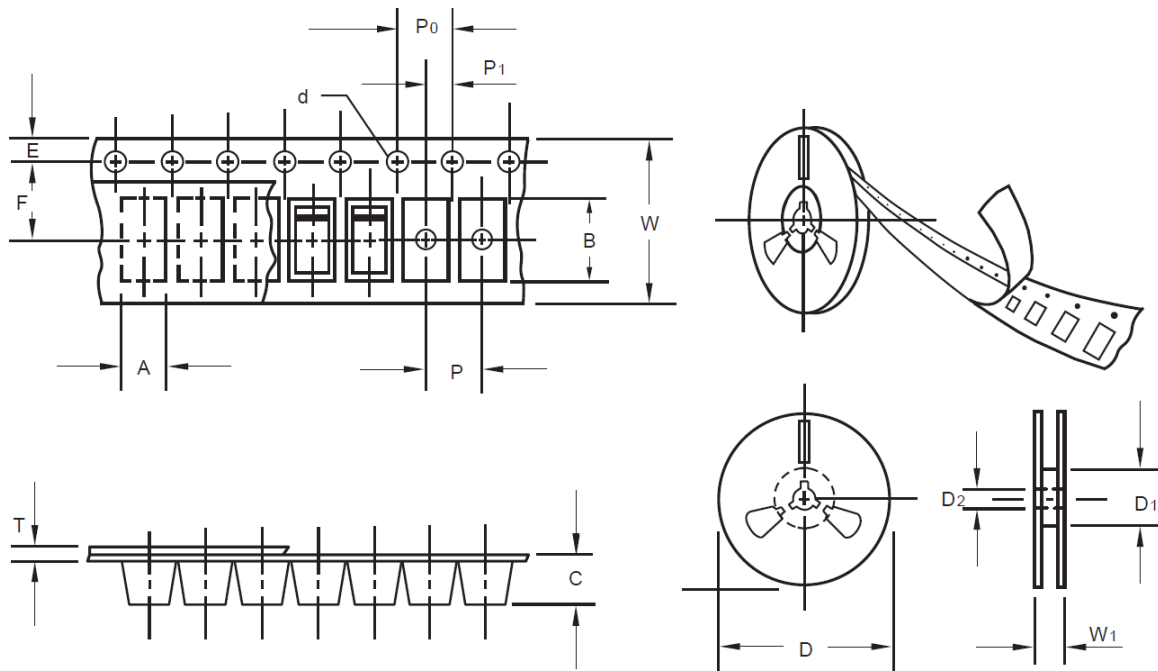
Fig.4 Typical Junction Capacitance



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TAPE/REEL (Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-A and specifications.

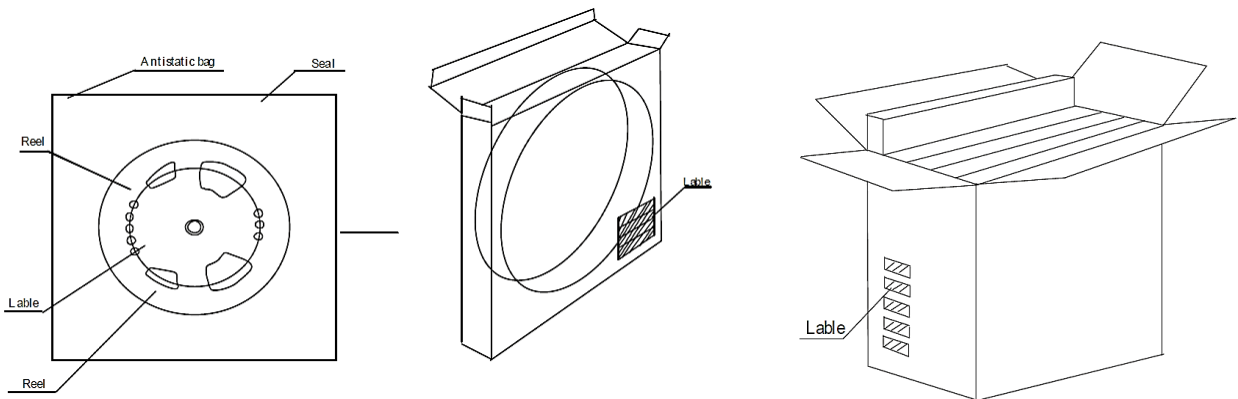


Item	Symbol	Tolerance	SO-323
Carrier width	A	0.1	2.10
Carrier Length	B	0.1	4.00
Carrier Depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
13" Reel outside diameter	-	-	-
13" Reel inner diameter	-	-	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	Min.	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W1	1.0	10.50

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PACKAGE

Case Code	Reel Size	MPQ (pcs)	Component Spacing (mm)	Qty. Per Box (pcs)	Inner Box L*W*H (mm)	Reel Size (mm)	Carton size L*W*H (mm)	Qty. Per Carton (pcs)	G. W (kg)
SOD-323	7"	3,000	-	24,000	210*208*203	178	400*400*250	180,000	8.0



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